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EMCORE Announces Advanced 10 Gbps Laser and Photodiode Optical Chip Solutions for Next-Generation Passive Optical Networks

ALHAMBRA, Calif., March 20, 2017 (GLOBE NEWSWIRE) -- EMCORE Corporation (NASDAQ:EMKR), a leading provider of advanced *Mixed-Signal Optics* products that provide the foundation for today's high-speed communication network infrastructures and leading-edge defense systems, announced today the introduction of a variety of advanced 10 Gbps DFB laser and APD chip solutions designed for XG-PON, XG-EPON and NG-PON2 Passive Optical Networks. The Company expects its latest chip offerings to represent a price/performance breakthrough for OLT (Optical Line Terminal) and ONU (Optical Networking Unit) applications. EMCORE will showcase its latest 10G chip solutions at OFC 2017, booth #3407, March 21-23 at the Los Angeles Convention Center, Los Angeles, CA.

EMCORE's latest G1013 series of 10 Gbps top and bottom illuminated APD & PIN photodiode chips have high-responsivity, low-capacitance, low dark current and are designed for low-cost, high-speed data communication receiving in fiber optic networks. The top illuminated models are available as tested die. The bottom illuminated coplanar APD & PIN photodiodes are tested to be mounted on a Chip-On-Block (COB) for ease of assembly into receiver modules. EMCORE will soon be introducing companion 10 Gbps laser chips with wavelength options of 1270 nm, 1310 nm and 1550 nm. EMCORE's 10G chip offerings feature advanced digital chip design, wide operating temperature range of -40^o to +85^o C, high optical output power, and are Telcordia Technologies[®] 468 and RoHS compliant.

"With these latest advancements in our 10G chip product line, we are poised to continue our growth as a merchant supplier of high-performance chips for a wide range of applications in the Telecom market and beyond," commented Jeffrey Rittichier, President and CEO of EMCORE. "In addition to next-gen PON applications, these latest chip offerings have application in 4G LTE+ and emerging 5G wireless networks," added Mr. Rittichier.

EMCORE's chip level devices are designed and manufactured at the Company's InP wafer fabrication facility in Alhambra, California. The plant features MOCVD reactors for 3x3" or 6x2" wafers, plus stepper, wafer track, RIE (Reactive Ion Etching), diffusion, metal and dielectric deposition, and cleaving and dicing equipment in a class 1,000 clean room space. EMCORE is the only chip supplier worldwide with a complete product portfolio of laser, APD and PIN photodiodes with an in-house wafer fab facility. The facility also functions as the Company's anchor for vertically-integrated manufacturing of its laser, transmitter and receiver products.

For more information on EMCORE chip level devices and our complete line of optical components, please visit us at OFC 2017, booth #3407, or at www.emcore.com. EMCORE will be meeting with customers, industry analysts and the media during the show, and invite you to contact us if you would like to schedule a meeting.

About EMCORE

EMCORE Corporation is a leading provider of advanced *Mixed-Signal Optics* products that provide the foundation for today's high-speed communication network infrastructures and leading-edge defense systems. Our optical chips, components, subsystems and systems enable broadband and wireless providers to continually enhance their network capacity, speed and coverage to advance the free flow of information that empowers the lives of millions of people daily. The *Mixed-Signal Optics* technology at the heart of our broadband transmission products is shared with our fiber optic gyros and military communications links to provide the aerospace and defense markets state-of-the-art systems that keep us safe in an increasingly unpredictable world. EMCORE's performance-leading optical components and systems serve a broad array of applications including cable television, fiber-to-the-premise networks, telecommunications, wireless infrastructure, satellite RF fiber links, navigation systems and military communications. EMCORE has fully vertically-integrated manufacturing capability through its world-class Indium Phosphide (InP) wafer fabrication facility at our headquarters in Alhambra, California and is ISO 9001 certified in Alhambra, and at our facilities in Warminster, Pennsylvania and China. For more information, please visit www.emcore.com.

Forward-looking statements:

The information provided herein may include forward-looking statements within the meaning of Section 27A of the Securities Act of 1933 and Section 21E of the Securities Exchange Act of 1934, as amended. Such statements include statements regarding EMCORE's plans, strategies, business prospects, growth opportunities, changes and trends in our business and expansion into new markets. These forward-looking statements are based on management's current expectations, estimates, forecasts and projections about EMCORE and are subject to risks and uncertainties that could cause actual results and events to differ materially from those stated in the forward-looking statements, including without limitation, the

following: (a) the rapidly evolving markets for EMCORE's products and uncertainty regarding the development of these markets; (b) EMCORE's historical dependence on sales to a limited number of customers and fluctuations in the mix of products and customers in any period; (c) delays and other difficulties in commercializing new products; (d) the failure of new products: (i) to perform as expected without material defects, (ii) to be manufactured at acceptable volumes, yields, and cost, (iii) to be qualified and accepted by our customers, and (iv) to successfully compete with products offered by our competitors; (e) uncertainties concerning the availability and cost of commodity materials and specialized product components that we do not make internally; (f) actions by competitors; and (g) other risks and uncertainties discussed under Item 1A - Risk Factors in our Annual Report on Form 10-K for the fiscal year ended September 30, 2015, as updated by our subsequent periodic reports. Forward-looking statements contained in this press release are made only as of the date hereof, and EMCORE undertakes no obligation to update or revise the forward-looking statements, whether as a result of new information, future events or otherwise.

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